

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Agarwal et al.

Application No. 09/590,795

Filed: June 8, 2000

For: METHODS FOR FORMING AND  
INTEGRATED CIRCUIT STRUCTURES  
CONTAINING RUTHENIUM AND TUNGSTEN  
CONTAINING LAYERS

Examiner: Cuong Q. Nguyen


Date: July 19, 2001



Art Unit: 2811

CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on July 19, 2001 as First Class Mail in an envelope addressed to: BOX NON-FEE AMENDMENT COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.

  
Attorney for Applicant

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F. JONES  
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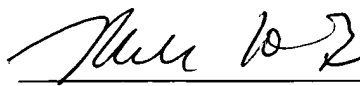
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**RESPONSE TO OFFICE ACTION**

In response to the Office Action of June 20, 2001, Applicants elect Claims 1-50 and 60-70 (Group II) for examination.

Respectfully submitted,

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